

Amendments to the Specification

Please revise the paragraph at page 3, lines 6-9, as follows:

According to an aspect of the present invention, there is provided a cleaning solution comprising about 5-30% by weight of fluoric salt, and about 20-10% by weight of organic acid, about 30-50% by weight of organic solvent, and about ~~50%~~ 20-50% by weight of water.

Please revise the paragraph at page 3, lines 10-15, as follows:

According to another aspect of the present invention, there is provided a method of cleaning ceramic parts on which plasma reaction by-products are adsorbed. The ceramic parts are dipped into a cleaning solution including about 5-30% by weight of fluoric salt, about 10-20% by weight of organic acid, about 30-50% by weight of organic solvent, and about ~~50%~~ 20-50% by weight of water. After rinsing the ceramic parts, the ceramic parts are treated with heat.

Please revise the paragraph at page 3, lines 16-25, as follows:

According to still another aspect of the present invention, there is provided a method of cleaning ceramic parts on which etching by-products are adsorbed as the result of etching a layer formed on a semiconductor substrate after introducing the substrate into a dry etching apparatus containing the ceramic parts. The method includes dipping the ceramic parts into a first cleaning solution including about 5-30% by weight of fluoric salt, about 10-20% by weight of organic acid, about 30-50% by weight of organic solvent, and about ~~50%~~ 20-50% by weight of water after separating the ceramic parts from the etching apparatus, and then dipping the ceramic parts into a second cleaning solution of sodium hydroxide aqueous solution. After rinsing the ceramic parts, the ceramic parts are treated with heat.

Please revise the paragraph at page 9, lines 14-16, as follows:

The cleaning solution of the present invention includes about 5-30% by weight of fluoric salt, about 10-20% by weight of organic acid, about 30-50% by weight of organic solvent, and about 50% 20-50% by weight of water.

Please amend the Abstract of the Disclosure as follows (a clean copy of the revised Abstract is submitted herewith on a separate page 11 of this paper):

Plasma reaction by products are removed from ceramic parts of semiconductor fabrication equipment by dipping the ceramic parts into a cleaning solution, rinsing the ceramic parts, and treating the ceramic parts with heat. The cleaning ~~Cleaning solution is used to clean ceramic parts using the same. The cleaning~~ solution includes about 5-30% by weight of fluoric salt, about 10-20% by weight of organic acid, about 30-50% by weight of organic solvent, and about 50% 20-50% by weight of water. The ceramic parts may be portions of an etching apparatus on which plasma reaction by-products are adsorbed. ~~Plasma reaction by products are removed from the ceramic parts dipping the parts into the cleaning solution, followed by rinsing and heat treatment.~~